



Investor Presentation

Commerzbank / ODDO BHF Corporate Conference

September 3, 2024

Disclaimer

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SUSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.



SUSS MicroTec at a glance



- Hidden champion headquartered in Germany with 75 years track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities
- 2025 Target: € 400 million revenue and >15% EBIT margin

304.3
in € million

Sales
2023

420.5
in € million

Order intake
2023

9.1%

EBIT margin
2023



CFO

Dr. Cornelia Ballwiesser

- Finance and Controlling
- Legal and Compliance
- Internal Audit
- Investor Relations
- IT
- ESG



CEO

Burkhardt Frick

- Sales and Service
- Strategy
- HR
- Business Units:
Advanced Backend Solutions,
Photomask Solutions



COO

Dr. Thomas Rohe

- R&D
- Purchasing
- Production
- Logistics
- Quality Management
- Product Center
- Facility Management

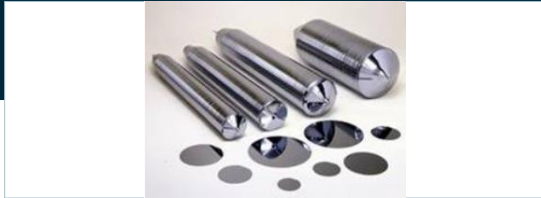
Our corporate vision defines our strategies

SUSS MicroTec Vision

**Leader in enabling innovative
advanced backend & photomask
solutions.**

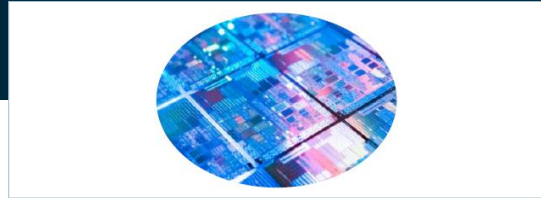
Our world are the semiconductor frontend and backend process steps

Wafer fabrication



Front-end-of-line

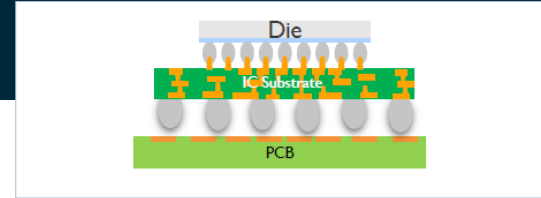
Wafer process



- Deposition/coating
- Cleaning
- **Patterning/lithography¹**
- Etching
- Implantation
- Annealing
- **Permanent bonding**
- **Temporary bonding**
- CMP polishing

From middle-of-line to back-end-of-line

Advanced packaging



- Deposition/coating
- Cleaning
- **Patterning/lithography**
- Etching
- Annealing
- CMP polishing
- **Permanent bonding**
- **Temporary bonding**
- **Wafer-level packaging**
- Wafer dicing
- Panel-level packaging

Final packaging



- Mounting
- Wire bonding
- Molding encapsulation
- Trim & forming

¹ Only related to Photomask processing
Source: Yole, Lithography and Bonding Equipment for More than Moore 2022

Advanced Backend Solutions is the core asset in our product portfolio

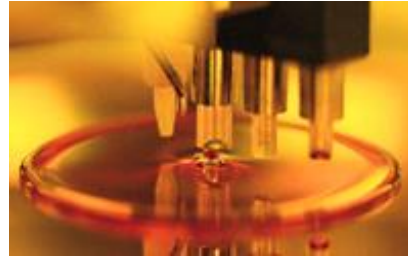
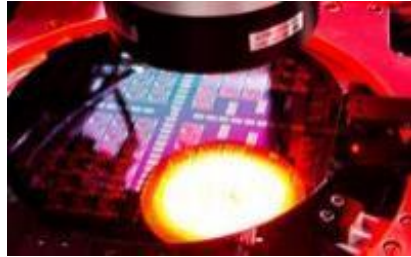
Frontend

Segments Photomask Solutions



Advanced Backend

Advanced Backend Solutions



Products

Photomask Equipment



MaskTrack X

Imaging

Mask Aligner
MA200/300



Projection
Scanner
DSC300

Coating



ACS300

Bonding

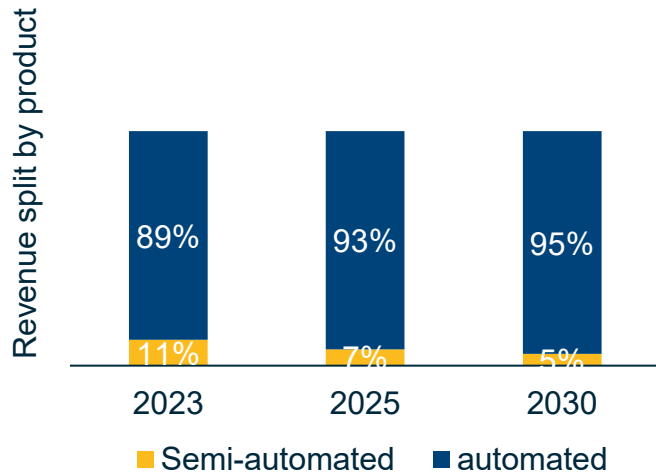
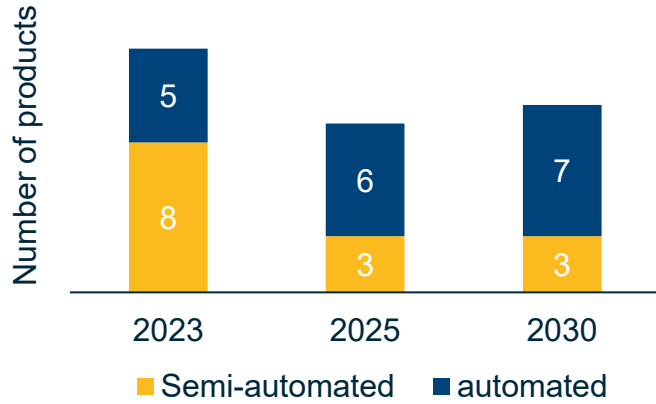
XBC300



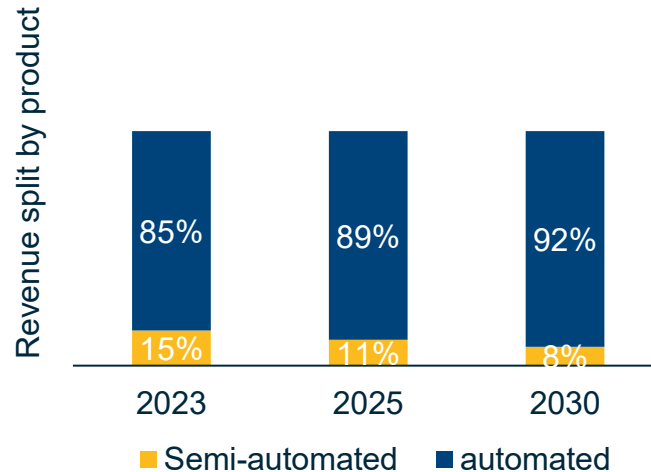
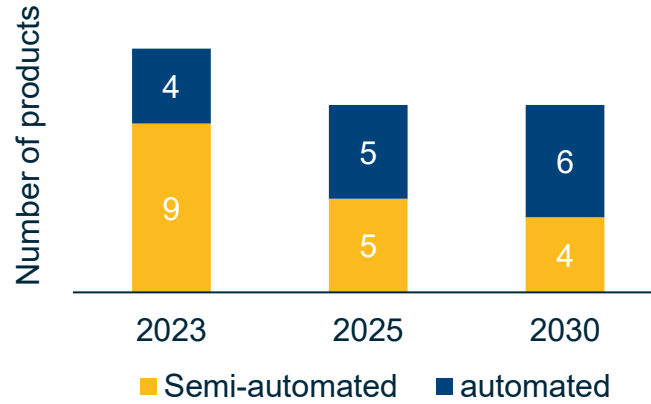
XB8

Focus on high-volume manufacturing markets while semi-automated tools will be phased-out during next years in Advanced Backend Solutions business unit

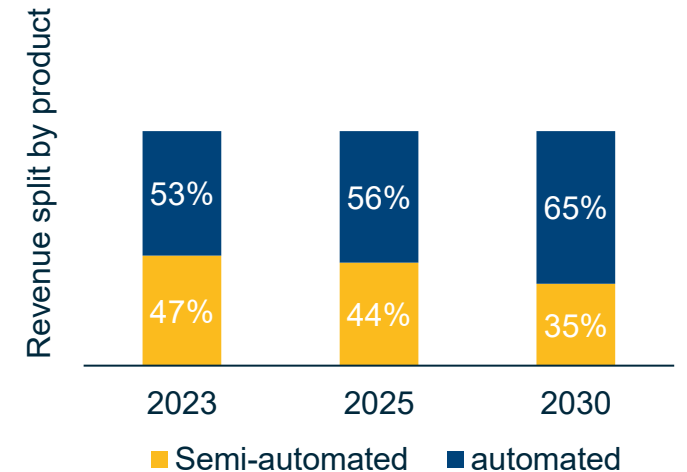
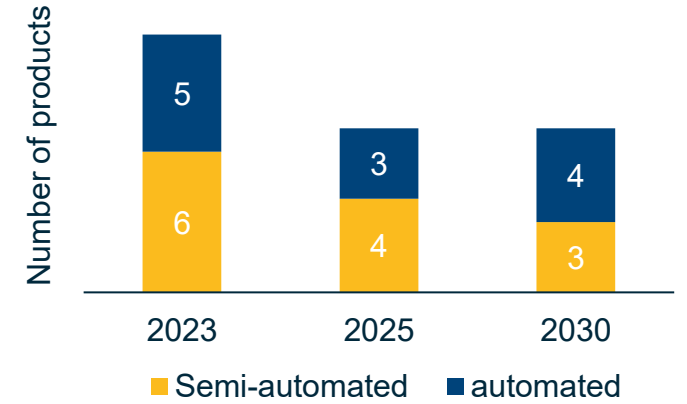
Bonding Systems



Coating Systems



Imaging Systems



Full range of bonding solutions by SUSS



Temporary Bonding

Temporary Bonding
XBS300



Permanent Bonding

Bonding (200mm)
XBS200



Hybrid Bonding

W2W (up to 200mm)
XBS200



W2W (up to 300mm)
XBS300 W2W



De-bonding / Cleaning
XBC300 Gen2



D2W & W2W
XBC300 Gen2 D2W/W2W



D2W
XBC300 Gen2 D2W



Mech. De-bonding (semi-auto)
DB12T



High-force Bonding (semi-auto)
SB8 Gen2 /XB8



We have built up additional temporary bonding capacity in Taiwan



- We added 50+ people in Hsinchu in order to increase manufacturing capacity for temporary bonders
- First temporary bonder 'made in Taiwan' has been completed at the beginning of March 2024
- Full capacity available as of Q3-2024
- Total manufacturing capacity for temporary bonding equipment (bonder, debonder and cleaner) in Sternenfels and Hsinchu allows us to generate yearly sales of ~ €150 million.

Wafer-to-wafer HB XBS300 W2W

Product launch: 10/2022
Target customers: HVM



Die-to-wafer/wafer-to-wafer HB XBC300 Gen2 D2W/W2W

Product launch: 05/2024
Target customers: research institutes,
R&D teams of HVM



Die-to-wafer HB XBC300 Gen2 D2W

Product launch: Q4/2024
Target customers: HVM



We optimize our product solutions to serve our customer’s device and manufacturing needs.

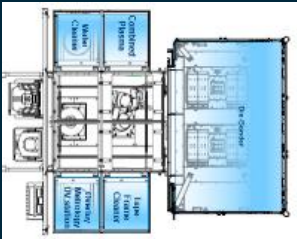
SUSS MicroTec's solutions for different hybrid bonding processing schemes

Wafer level processing



Single die processing

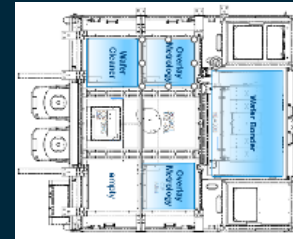
Surface Preparation (SP) & D2W



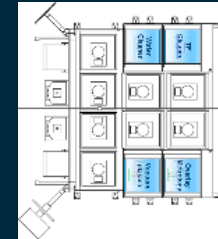
SP & D2W/W2W



SP & W2W



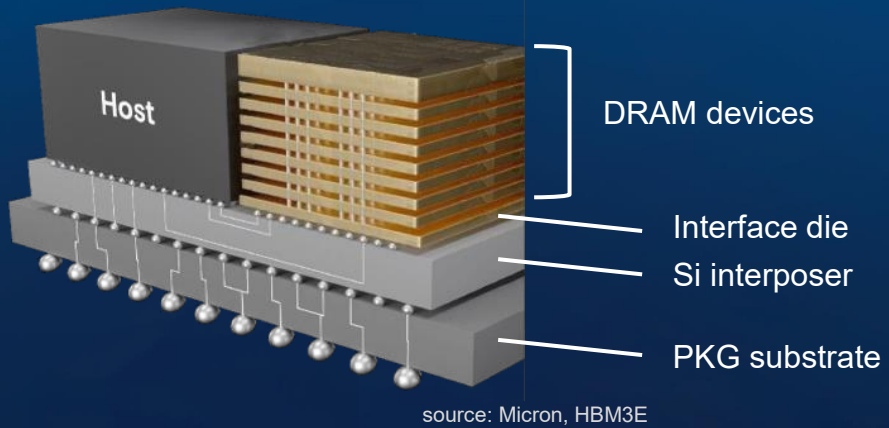
SP only



Overlay only



HBM roadmap enables SUSS to grow in existing and new markets



	HBM3E	HBM4	HBM4E	HBM5
Expected SOP	2024	2025	2026 or 2027	2027 or 2028
# of DRAM layer acc. to JEDEC	8/12	12	16	16/20
Bonding type in DRAM stack	TCB	TCB	TCB or HB	HB
Thinning of DRAM devices	TBDB	TBDB	TBDB	TBDB

Relevance for SUSS:

TBDB remains a crucial process for thinning of DRAM devices used in HBM cube

Growth of existing SUSS TBDB business in line with general HBM market growth

Increase of layer number in HBM cube triggers more TBDB capacity for thinning of DRAM devices

Additional growth of SUSS TBDB business in line with higher layer in HBM cube

Hybrid bonding will gradually replace Thermal Compression bonding for stacking of DRAM devices

Expansion into this market offers new growth opportunities with SUSS HB solutions

TCB: Thermal compression bonding, HB: hybrid bonding, TBDB: Temporary bonding & de-bonding

Based on the strong H1 performance, we have raised our forecast for 2024

Guidance 2024 (as of July 18, 2024)



Initial guidance:
Sales of € 340-370 million



Initial guidance:
Gross profit margin of 35-38%



Initial guidance:
EBIT margin of 10-12%

Financial Results

H1 2024*

192.2

in € million

Order intake
H1 2024

+7.9% YoY

192.8

in € million

Sales
H1 2024

+45.6% YoY

39.8

in %

Gross profit margin
H1 2024

+4.2pp YoY

15.6

in %

EBIT margin
H1 2024

+6.9pp YoY

*Adjusted for divested MicroOptics business

Key CEO messages



- Execution of well-filled order book was very successful in H1 2024 with growth of 45.6% and increased gross profit margin and EBIT margin.
- We are confident that our strong performance will continue in H2 2024. As a result, we have raised our guidance for all three financial KPIs.
- Based on the high order book level of €450 million, we will continue to push ahead with the expansion of flexible production capacity and measures to increase operational efficiency.

SUSS is committed to be a strong partner for further growth and we are working hard to further accelerate our ability to deliver from our manufacturing facilities in Germany and Taiwan.

Strong growth and improving profitability in H1 2024

In € million	H1 2024	H1 2023	Change
Order intake	192.2	178.2	+ 7.9%
Order book as of June 30	450.0	381.5	+ 18.0%
Sales	192.8	132.4	+ 45.6%
Gross profit	76.8	47.1	+ 63.1%
Gross profit margin	39.8%	35.6%	+ 4.2pp
EBIT	30.1	11.5	+ 161.7%
EBIT margin	15.6%	8.7%	+ 6.9pp
Earnings after taxes (continuing operations)	22.5	9.4	+139.4%
Net profit*	80.8	6.2	--
Earnings per share, basic (in €), continuing operations	1.18	0.49	+ 140.8%
Earnings per share, basic (in €)*	4.23	0.32	--
Net cash	121.0	40.2	+ 201.0%
Free cash flow (continuing operations)	22.6	5.1	+ 443.1%
Free cash flow total*	93.3	1.1	--
Employees as of June 30	1,310	1,105	+ 18.6%

*Not adjusted for divested MicroOptics business

- Order intake grew year-on-year in the first six months, Q2 2024 slightly below Q1 2024 but above the level of Q2 2023.
- Favorable product mix and a disproportionately low increase in OPEX resulted in a positive development of gross profit margin and EBIT margin.
- Net profit includes extraordinary income from MicroOptics sale (€ 58.8 million); earnings from continuing operations also significantly higher.
- Improved free cash flow from continuing operations demonstrates ability to convert higher volume and margin improvements into cash.
- Expansion of headcount mainly driven by new employees for production in Germany and Taiwan and R&D.

Division Overview H1 2024

Advanced Backend Solutions

in € million	H1 2024	H1 2023
Order intake	130.4	93.5
Order book	280.4	200.2
Sales	136.0	97.8
Gross profit	57.5	36.5
Gross profit margin	42.3%	37.3%
EBIT	21.3	9.1
EBIT margin	15.7%	9.4%

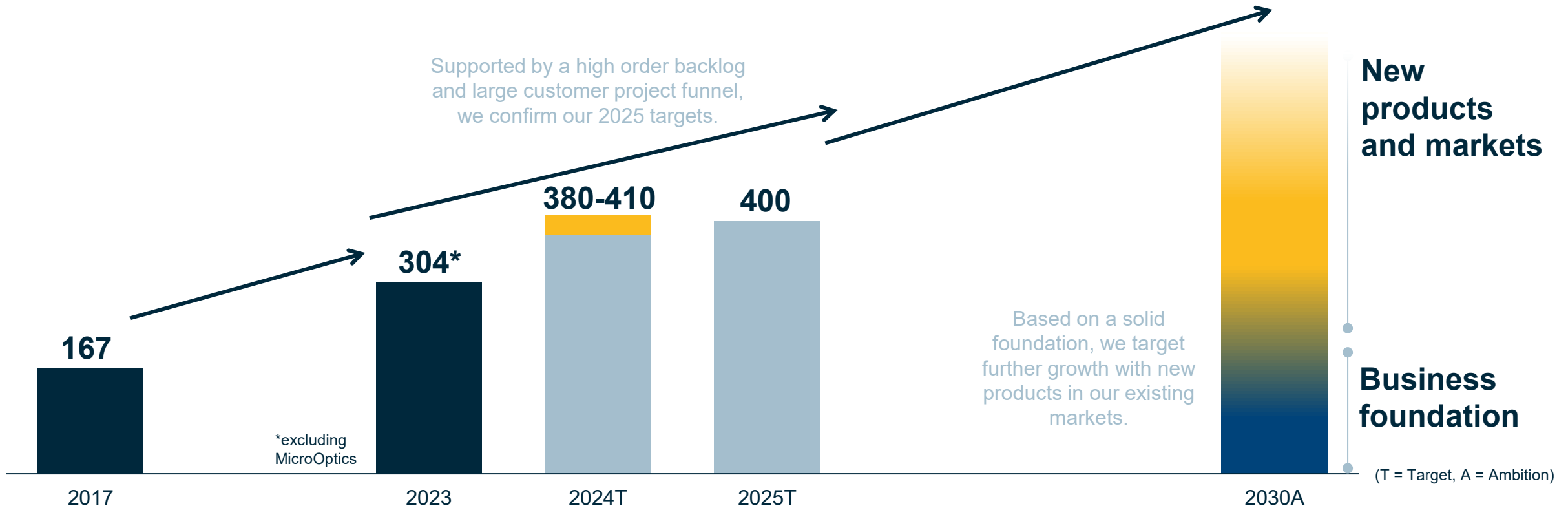
Photomask Solutions

in € million	H1 2024	H1 2023
Order intake	61.8	84.7
Order book	169.9	181.4
Sales	56.8	34.5
Gross profit	19.6	10.7
Gross profit margin	34.5%	30.9%
EBIT	11.0	4.4
EBIT margin	19.4%	12.6%

- Continued order intake momentum from our Bonder product line, especially for temporary bonding equipment; order from US-based technology partner BRIDG for our D2W/W2W hybrid bonding platform
- Significant sales growth, mainly driven by execution of bonder orders received in H2 2023
- Unchanged softness in Imaging and Coating product line
- Gross profit margin and EBIT margin increase as a result of favorable product mix and under-proportional increase in OPEX

- Order intake on a lower level than in H1 2023, but order book still exceeds annual production capacity
- Strong order book level of ~€170 million provides high visibility through mid-2025
- Increased profitability due to a very favorable product and customer mix
- Small number of systems sold can result in greater volatility due to changes in product and customer mix

Based on our business foundation we see further potential beyond



Major growth drivers 2023

- Converting high order backlog in Photomask Solutions and Bonder business into sales growth

Major growth drivers 2024/2025

- Bonding (especially with regard to AI-driven demand for temporary bonders)
- Photomask Solutions

Major growth drivers 2030

- General expected market growth in our core businesses (lithography, bonding, photomask)
- Hybrid Bonding
- Wafer Cleaning

Investor Relations Information

Contact

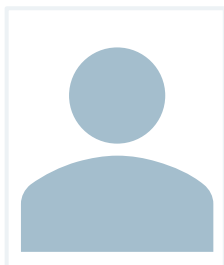


**Sven
Köpsel**

VP Investor Relations &
Communications

Tel. +49 89 32007-151

E-mail sven.koepsel@suss.com



**Florian
Mangold**

Manager
Investor Relations

Tel. +49 89 32007-306

E-mail florian.mangold@suss.com

Financial Calendar 2024



March 27
Annual Report 2023



May 8
Q1 Report 2024



June 11
Annual General Meeting 2024



August 7
Half Year Report 2024



November 7
Nine Months Report 2024